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**Sasaki**

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(54) **POSITIVE RESIST COMPOSITION AND  
PATTERN FORMING METHOD USING THE  
SAME**

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See application file for complete search history.

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(57) **ABSTRACT**

A positive resist composition satisfying high sensitivity, high  
resolution and good line edge roughness at the same time, and  
a pattern forming method using the resist composition are  
provided, which are a positive resist composition comprising  
(A) a resin which becomes soluble in alkali developer  
increases under the action of an acid, the resin having two  
kinds of repeating units each having a specific styrene skel-  
eton, (B) a compound of generating an acid upon irradiation  
with actinic rays or radiation, and (C) an organic basic com-  
pound, and a pattern forming method using the resist compo-  
sition.

**17 Claims, No Drawings**